

Herschel/Planck

**INSTRUMENT INTERFACE DOCUMENT
PART B**

INSTRUMENT "SPIRE"

Name		Signature
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To: Alcatel/ESA/Astium EADS

SCI-PT-IIDB/Spire-02124 issue 3.2 sign off notes.

From: John Delderfield

cc. Eric Sawyer, Matt Griffin

SPIRE IID-B v 3.2

To define a baseline CDR position Spire Project agreed at the last progress meeting to sign off on this version, subject to the ESA control board recommendations and subject to our tabling a list of items in the documents that we know need progressing as normal work. This is that list.

Lastly by way of introduction, sending E-mails that omit to mention these caveats is unhelpful and detracts rather than adds to the process.

Since taking it, on Guy.Doubrovik of Alcatel has done an excellent job of controlling and updating this document, and Spire thanks him for his work, approach and patience.

Checking the updates 3.0 to 3.1 to 3.2, there are just a few points arising but overall this tidying has worked well despite much of it only being in the Document change record, not tracked by ECRs.

p 0-11

Change to section 5.7.1.3, should be “information” not “informations” and also on page 5-19.

Change to section 5.11.1.2. This is not what it seems and Spire does NOT accept it. There is a very long standing agreement to the requirement for this capability and the TBC insertion breaks this.

Change to section 5.14.3 is on page 5-43 not 5-44.

p 2-1

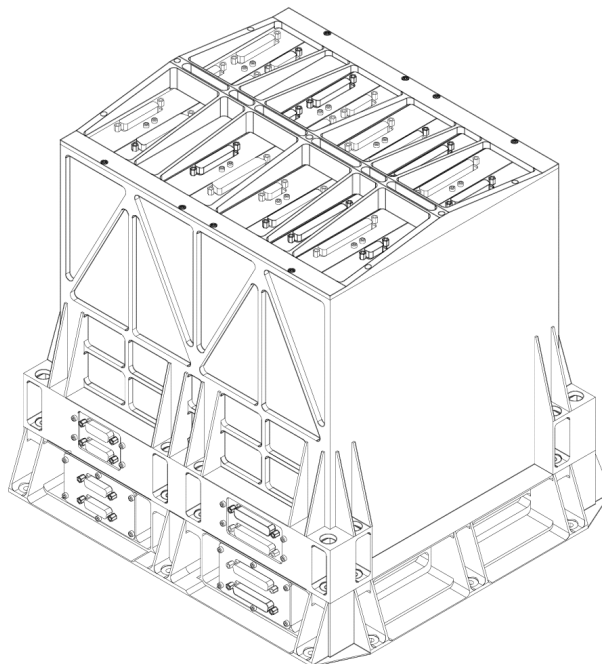
Twice, one word “hereafter”, not “here after”.

p 5-3

Note that Spire is at 5-7 not 5-6, but changes are not to any IID-B I/Fs so this is not IID-B important

p 5-11

Figure 5.4-8. HSFCU has webbed feet and looks like:

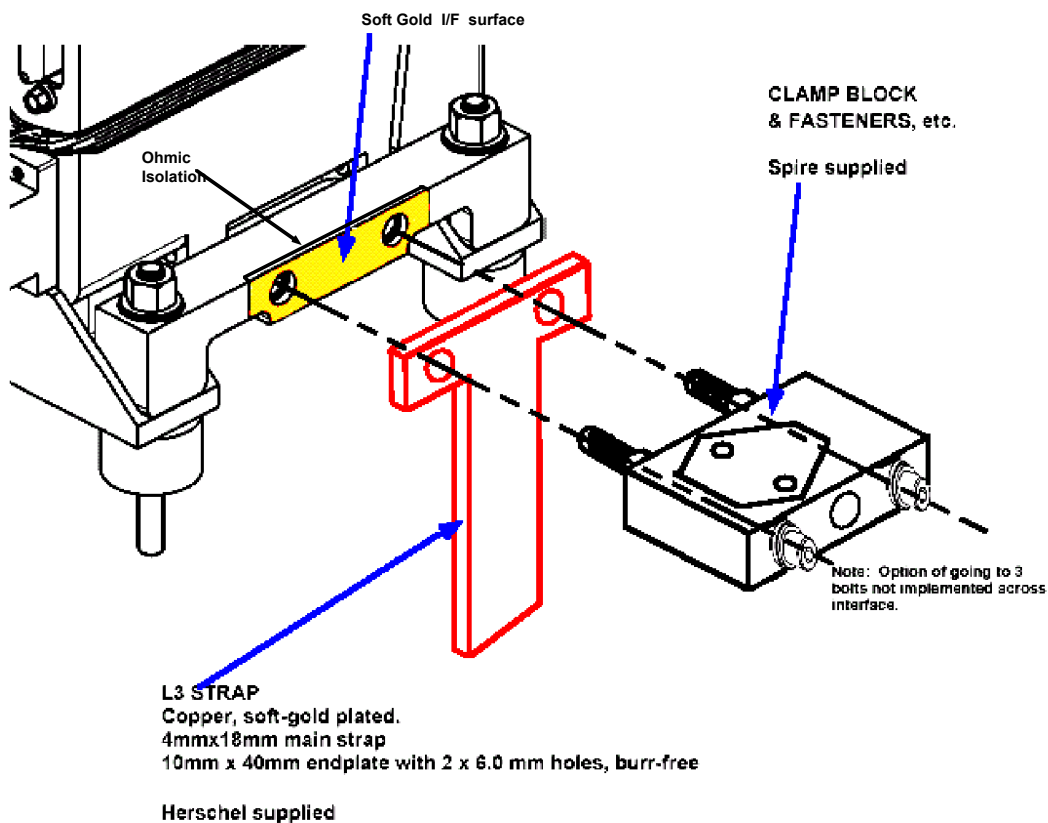


p 5-12

Remove line referencing SPIRE-RAL-DWG-001409 as it repeats the line below and calls up an out of date issue, and add "SPIRE-RAL-DWG-001409" after annex 1 to this line below.

p 5-14

Change words "Kapton Tape" in 7th paragraph to "Ohmic isolation", and drop in this updated diagram:



p 5-17. remove issue 2.3 from reference to reduced TMM, a. so text is more generalised, and b. because we are on issue 2.5 already anyway.

p 5-18. First paragraph, remove superstition; change "witch" to "which". But more importantly, this whole paragraph has errors: MN-3513 on 5/9 is entitled a Progress and I/F meeting not Convergence and MN 3961 is likewise on 18/11. It needs to be much clearer that the ethos of section 5.7.1 arises from the ESTEC meeting convened by Chris Jewell. Spire refers Alcatel to RAL's inputs to the minutes of that meeting.

p 5-23

Remove reference to SPIRE reduced TMM as it is repeated in page 5-17 and not much use tucked away in a section on temperature sensors.

p 5-25 Remove note at bottom of section 5.9.1 as 2.5 TMM is not a future item....delivered end January.

p 5-30. RAL does intend to issue HDD 1.2 which will amalgamate 1.1 with NOT 1819 issue 3.

p 5-38. REQ-0200 is wrong. Recent E-mail corrects.

p 5-46 Remove Note 2 . Done.

P 5-44. Section 5.15.1.2. The goal is now less demanding than the requirement and should be deleted.

Annexes: Please note that Document pack 10 and RTMM 2.5 are out, and that pack 10 travels with a covering E-mail that spells out a few future developments.